

Wafer Remounter

RAD-2600F/12



Outline

- Fully-automatic wafer remounter that is designed to laminate a dicing tape to the opposite side of a wafer that is already mounted on a ring frame and dicing tape; then the original dicing tape is removed (transfer mount).
- A 6-jointed robot arm is used to cut the mounted tape before laminating the new tape, therefore, there is no adhesion between the two tapes.
- The tape cutting and wafer remounting process are all performed on the same table.

Options

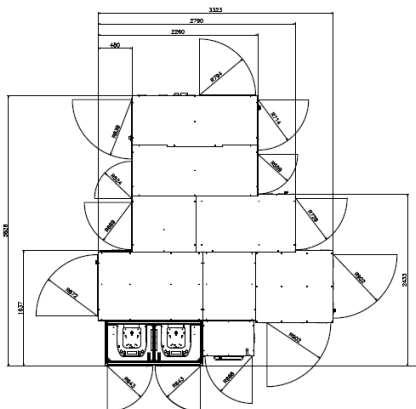
- Dicing Tape In-Line Pre-Cutting
- Host Communication Function(Communication Format: Conforms to SECS-I and HSMS/Software: Conforms to GEM)
- Vision System (Wafer ID Reader & Barcode Attachment System)
- OHT Compatible
- Ceiling FFU Installation

Suitable Tape

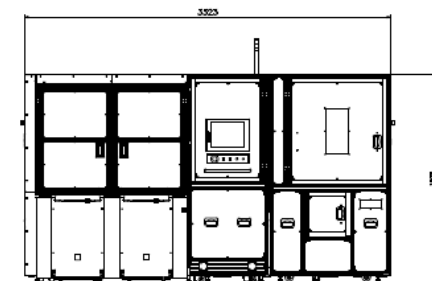
- Dicing Tape: Adwill D Series, G Series
- Peeling tape for BG Tape: Adwill S Series

External View

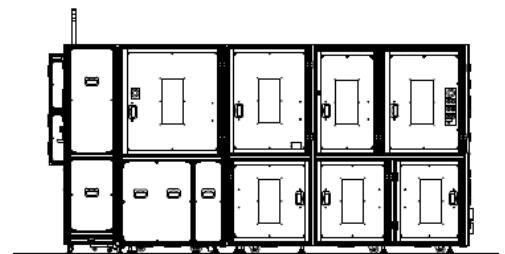
Unit:mm



Top View



Front View



Right Side View

Facility

Power Supply	Voltage	: AC200-230V±10% (AC190-253V)
	Frequency	: 50/60Hz
	Phase	: 3 phase
Air Supply	Power consumption	: 12kW
	Air pressure	: 0.6-0.8MPa
	Air consumption	: <800L/min (ANR)
Vacuum Supply	Vacuum pressure	: <-80kPa

Applicable Wafer Size

300mm (*200 mm is optional)

Size

Width(W) : 3,323mm
Depth(D) : 3,828mm
Height(H) : 2,227mm
(excluding the signal tower and protruding parts)

Weight

3,700kg

UPH

30wafers/hour

The above processing capacity is based on following conditions:

Wafer	: 300mm non-polished mirror wafer
Dicing tape	: D-675 from LINTEC



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